



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-05-25
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99PM72PXPTR	H6EH*UK39BB6	A	959	2020-05-25
	Amount	UoM	Unit type	ST ECOPACK Grade
	485	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	CD00357319	



Package Designator	Size	Nbr of instances	Shape	
QFP	10.30,7.50,2.28	36	gull wing	
Comment	PowerSSO36. MDF valid for CPs: L99PM72PXP,L99PM72PXPTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.09	die	188
Lead	7.48	soft solder	15409

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	7.48	Soft solder	15409
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	7.478	Soft solder	974967

Material Composition Declaration :						Mfr Item Name	H6EH*UK39BB6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	18.799	mg	supplier	die	Silicon(Si)	7440-21-3		17.922	mg	953348	36929
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.118	mg	6277	243
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.010	mg	532	21
				supplier	metallisation	Gold(Au)	7440-57-5		0.027	mg	1436	56
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.091	mg	4841	188
				supplier	metallisation	Tungsten(W)	7440-33-7		0.187	mg	9947	385
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.029	mg	1543	60
				supplier	passivation	Silicon oxide	7631-86-9		0.276	mg	14682	569
				supplier	polymer coating	Polyimide	Proprietary		0.139	mg	7394	286
				Leadframe	M-004 Copper and its alloys	159.665	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8	
supplier	alloy & coating	Iron(Fe)	7439-89-6						3.655	mg	22892	7531
supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8						0.220	mg	1378	453
supplier	alloy & coating	Zinc(Zn)	7440-66-6						0.191	mg	1196	394
supplier	alloy & coating	Silver (Ag)	7440-22-4						0.209	mg	1309	431
Soft solder	Solder	7.670	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	7.478	mg	974968	15408
				supplier	solder	Silver(Ag)	7440-22-4		0.115	mg	14993	237
				supplier	solder	Tin(Sn)	7440-31-5		0.077	mg	10039	159
Bonding wires	M-008 Precious metals	1.933	mg	supplier	wire	Gold(Au)	7440-57-5		1.931	mg	998966	3979
	M-004 Copper and its alloys			supplier	wire	Copper(Cu)	7440-50-8		0.001	mg	517	2
				supplier	wire	Palladium(Pd)	7440-05-3		0.001	mg	517	2
Encapsulation	M-011 Other inorganic materials	292.981	mg	supplier	mold compound	Silica vitreous	60676-86-0		259.288	mg	885000	534283
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		15.528	mg	53000	31997
				supplier	mold compound	Phenol resin	205830-20-2		11.719	mg	39999	24148
				supplier	mold compound	Epoxy type resin	proprietary		5.860	mg	20001	12075
				supplier	mold compound	Carbon black	1333-86-4		0.586	mg	2000	1208
connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	8762